MA6X123 (MA123)

Silicon epitaxial planar type

For switching circuit

■ Features

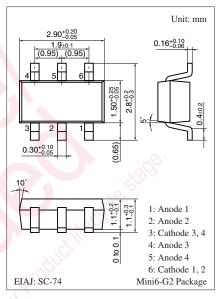
- Four isolated elements contained in one package, allowing highdensity mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V _{RM}	80	V
Forward current *1	I_{F}	100	mA
Peak forward current *1	I_{FM}	225	mA
Non-repetitive peak forward surge current *1, 2	I _{FSM}	500	mA
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *1: Value for single diode

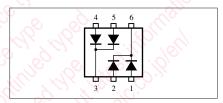
*2: t = 1 s



Marking Symbol: M2B

Internal Connection

Note) The part number in the parenthesis shows conventional part number.

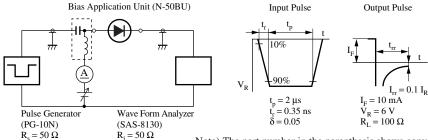


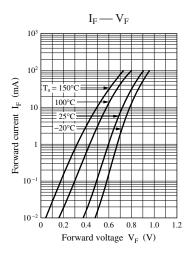
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

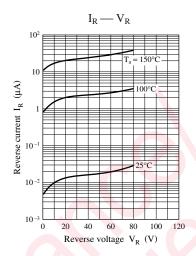
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	I _F = 100 mA	1.90		1.2	V
Reverse voltage	V_R	$I_R = 100 \mu A$	80			V
Reverse current	I_R	V _R = 75 V			100	nA
Terminal capacitance	C _t	$V_R = 0 \text{ V, f} = 1 \text{ MHz}$			2	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
"VSI		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

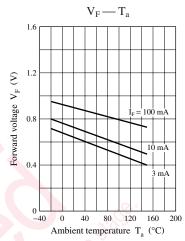
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

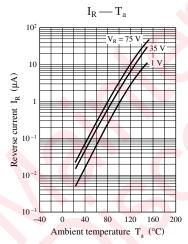
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *: t_{rr} measurement circuit

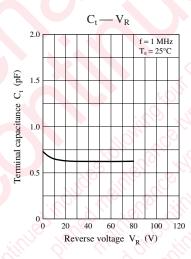


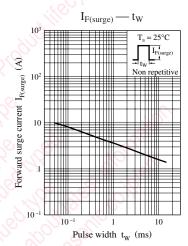












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